

New Product: Microbond® DA5118 D No Clean High Lead Dispensing Solder Paste

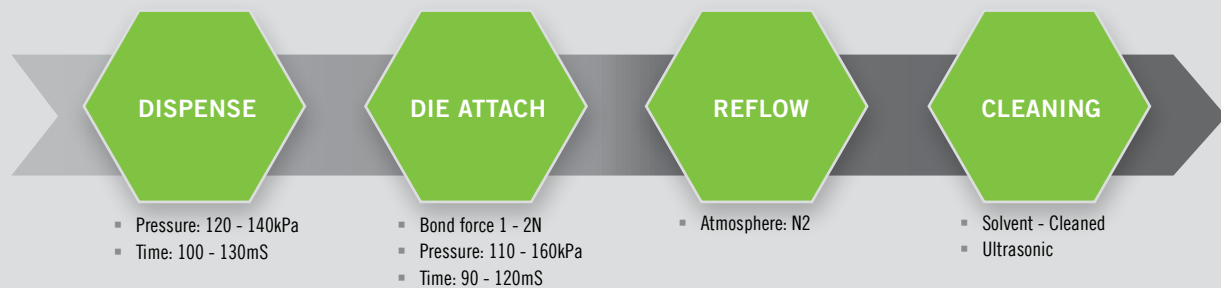
DA5118 D is No Clean High Lead Solder Paste designed for use in die, clip and bridge applications. Its stable rheology provides exceptional dispensing performance suitable for high volume production and high density leadframe applications. The paste exhibits long work life, low void rates and easy cleanability.

DA5118 D Benefits

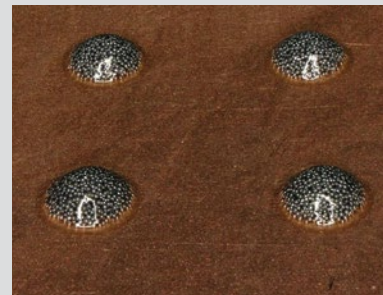
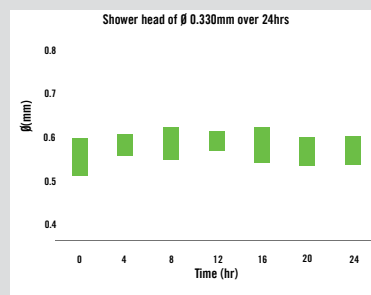
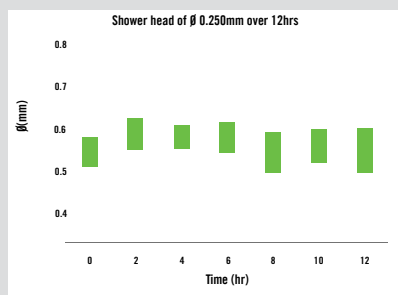
- Halogen zero
- Stable rheology
- Exceptional dispensing consistency
- Wide reflow temperature window
- Low void rates
- Easy cleanability
- Long work life
- Long pot life



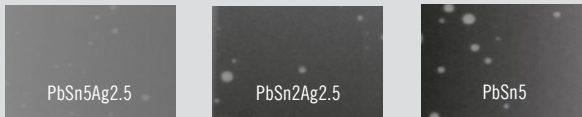
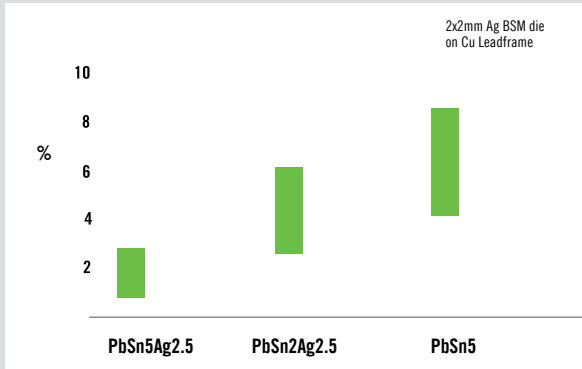
DA5118 D Solder Paste Process and Application



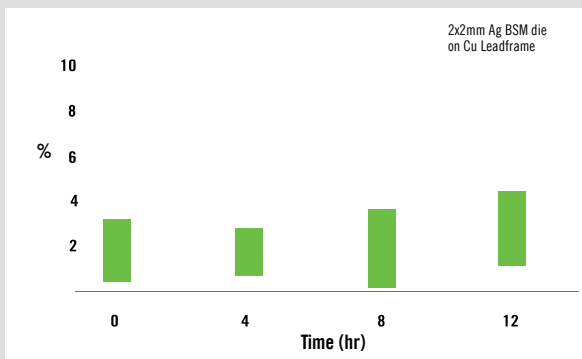
Continuous Dispensing Performance



Voids Performance - Alloy



Voids Performance - Over Time



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Product Properties Table

Physical Properties	DA5118 D
Alloy	PbSn2Ag2.5 (Type 3)
	PbSn5Ag2.5 (Type 3)
	PbSn5 (Type 4)
Metal Content	87%
Halogen Content	Halogen-zero
Flux Activity	ROLO
Application/Process	
Dispensing (min Dia)	Yes (Ø 0.25mm)
Reflow Temperature	360 - 390°C
Reflow Atmosphere	N2
Features & Benefits	
Cleaning	Solvent Clean
Work Life	12 hr
Shelf Life	6 mths
	4 mths (PbSn2Ag2.5)
Storage Condition	2 - 10°C
	-10 - 5°C (PbSn2Ag2.5)

Viscosity Performance

